

## **Maximum Ratings** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			$V_{DSS}$	-20	V
Gate-Source Voltage			$V_{GSS}$	±6	V
Continuous Drain Current (Note 4) V <sub>GS</sub> = -4.5V	Steady State	$T_A = 25$ °C $T_A = 85$ °C	I <sub>D</sub>	-1.03 -0.68	Α
Pulsed Drain Current (Note 5)			I <sub>DM</sub>	-3	Α

### **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 4)	$P_{D}$	530	mW
Thermal Resistance, Junction to Ambient @T <sub>A</sub> = 25°C (Note 4)	R <sub>0JA</sub>	235	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

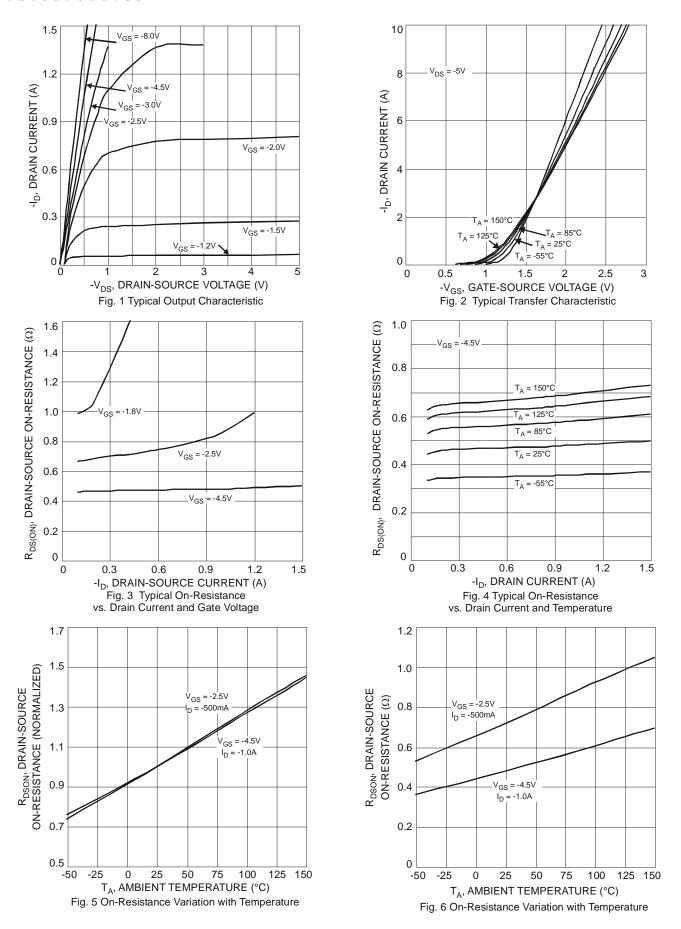
## Electrical Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Tym	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 6)	Symbol	IVIIII	Тур	IVIAX	Unit	rest Condition	
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-20	_	_	V	$V_{GS} = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current T <sub>J</sub> = 25°C	I <sub>DSS</sub>	-	_	-100	nA	$V_{DS} = -20V, V_{GS} = 0V$	
Gate-Source Leakage		_	_	±2.0	μA		
Gate-Source Leakage $I_{GSS}$ $\pm 2.0$ $\mu$ A $V_{GS} = \pm 4.5 \text{V}, V_{DS} = 0 \text{V}$ ON CHARACTERISTICS (Note 6)					VGS = ±4.5V, VDS = 0V		
Gate Threshold Voltage	V <sub>GS(th)</sub>	-0.5	l -	-1.0	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
Cate Thiodheld Voltage	V G3(III)	-	0.5	0.75	Ω	$V_{GS} = -4.5V$ , $I_D = -430mA$	
			0.7	1.05		$V_{GS} = -2.5V$ , $I_D = -300$ mA	
Static Drain-Source On-Resistance	P== (=+)		1.0	1.5		$V_{GS} = -1.8V$ , $I_D = -150$ mA	
Static Dialit-Source Off-Nesistance	R <sub>DS</sub> (ON)		1.0	20		, -	
			-	25		$V_{GS} = -1.7V, I_D = -100mA$	
5 JT ( A) W			-	25		$V_{GS} = -1.5V, I_{D} = -100mA$	
Forward Transfer Admittance	Y <sub>fs</sub>	-	0.9	-	S	$V_{DS} = -10V, I_{D} = -250mA$	
Diode Forward Voltage	$V_{SD}$		-0.8	-1.2	V	$V_{GS} = 0V, I_{S} = -150mA$	
DYNAMIC CHARACTERISTICS (Note 7)							
Input Capacitance	C <sub>iss</sub>	-	59.76	-	pF	V <sub>DS</sub> = -16V, V <sub>GS</sub> = 0V, f = 1.0MHz	
Output Capacitance	Coss	-	12.07	-	pF		
Reverse Transfer Capacitance	Crss	-	6.36	-	pF		
Total Gate Charge	Qq	-	622.4	-	рC	$V_{GS} = -4.5V$ , $V_{DS} = -10V$ , $I_{D} = -250$ mA	
Gate-Source Charge	Qgs	-	100.3	-	рС		
Gate-Drain Charge	Q <sub>qd</sub>	-	132.2	-	рС		
Turn-On Delay Time	t <sub>D(on)</sub>	-	5.1	-	ns		
Turn-On Rise Time	t <sub>r</sub>	-	8.1	-	ns	V <sub>DD</sub> = -10V, V <sub>GS</sub> = -4.5V,	
Turn-Off Delay Time	t <sub>D(off)</sub>	-	28.4	-	ns	$R_L = 47\Omega$ , $R_G = 10\Omega$ , $I_D = -200$ mA	
Turn-Off Fall Time	t <sub>f</sub>	-	20.7	-	ns		

Notes:

- 4. Device mounted on FR-4 PCB, with minimum recommended pad layout.
- 5. Repetitive rating, pulse width limited by junction temperature.6. Short duration pulse test used to minimize self-heating effect.7. Guaranteed by design. Not subject to production testing.







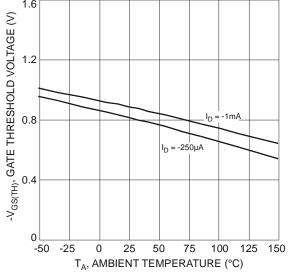
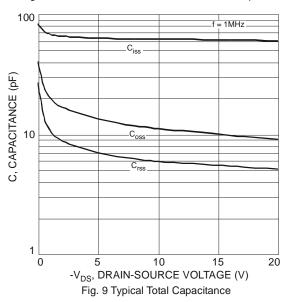
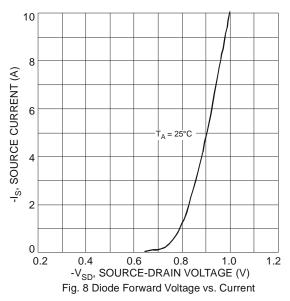


Fig. 7 Gate Threshold Variation vs. Ambient Temperature





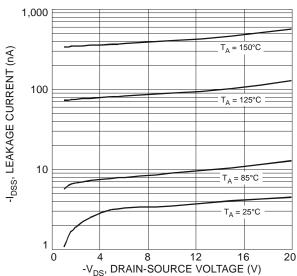


Fig. 10 Typical Leakage Current vs. Drain-Source Voltage

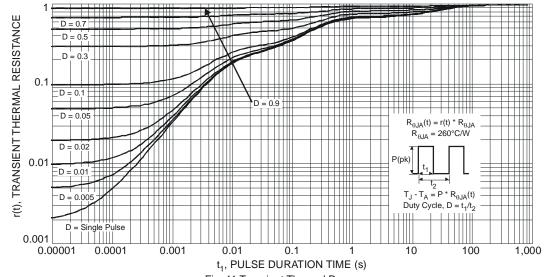
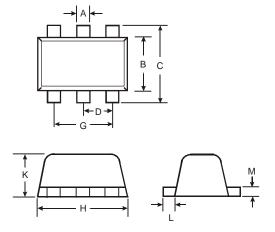


Fig. 11 Transient Thermal Response

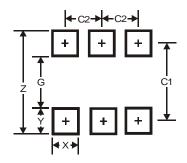


# **Package Outline Dimensions**



SOT563					
Dim	Min	Max	Тур		
Α	0.15	0.30	0.20		
В	1.10	1.25	1.20		
С	1.55	1.70	1.60		
D	-	-	0.50		
G	0.90	1.10	1.00		
Н	1.50	1.70	1.60		
K	0.55	0.60	0.60		
L	0.10	0.30	0.20		
M	0.10	0.18	0.11		
All Dimensions in mm					

## **Suggested Pad Layout**



Dimensions	Value (in mm)
Z	2.2
G	1.2
Х	0.375
Y	0.5
C1	1.7
C2	0.5



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